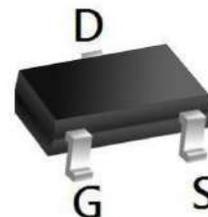


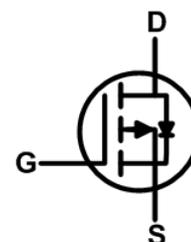
## P-Ch 30V Fast Switching MOSFETs

### Features:

- ★ Green Device Available
- ★ Super Low Gate Charge
- ★ Excellent CdV/dt effect decline
- ★ Advanced high cell density Trench technology



### SOT23S Pin Configurations



### Description:

The KN3601S is the high cell density trenched P-ch MOSFETs, which provides excellent RDSON and efficiency for most of the small power switching and load switch applications.

The KN3601S meet the RoHS and Green Product requirement with full function reliability approved.

### Product Summary

BVDSS	RDSON	ID
-30V	53mΩ	-4.3A

### Absolute Maximum Ratings

Symbol	Parameter	Rating	Units
$V_{DS}$	Drain-Source Voltage	-30	V
$V_{GS}$	Gate-Source Voltage	$\pm 12$	V
$I_D@T_A=25^\circ C$	Continuous Drain Current	-4.3	A
$I_D@T_A=70^\circ C$	Continuous Drain Current	-3.6	A
$I_{DM}$	Pulsed Drain Current <sup>2</sup>	-20	A
$P_D@T_A=25^\circ C$	Total Power Dissipation <sup>3</sup>	1.4	W
$P_D@T_A=70^\circ C$	Total Power Dissipation <sup>3</sup>	0.9	W
$T_{STG}$	Storage Temperature Range	-55 to 150	$^\circ C$
$T_J$	Operating Junction Temperature Range	-55 to 150	$^\circ C$

### Thermal Data

Symbol	Parameter	Typ.	Max.	Unit
$R_{\theta JA}$	Thermal Resistance Junction-Ambient <sup>1</sup>	---	125	$^\circ C/W$
$R_{\theta JA}$	Thermal Resistance Junction-Ambient <sup>1</sup> (t $\leq 10s$ )	---	85	$^\circ C/W$

Symbol	Parameter	Conditions	Min	Typ.	Max.	Unit
$BV_{DSS}$	Drain-Source Breakdown Voltage	$V_{GS}=0V, I_D=-250\mu A$	-30	---	---	V
$\Delta BV_{DSS}/\Delta$	$BV_{DSS}$ Temperature Coefficient	Reference to 25°C, $I_D=-1mA$	---	-	---	V/°C
$R_{DS(ON)}$	Static Drain-Source On-Resistance <sup>2</sup>	$V_{GS}=-10V, I_D=-3A$	---	---	53	mΩ
		$V_{GS}=-4.5V, I_D=-3A$	---	---	60	
		$V_{GS}=-2.5V, I_D=-2A$	---	---	80	
$V_{GS(th)}$	Gate Threshold Voltage	$V_{GS}=V_{DS}, I_D=-250\mu A$	-	---	-1.2	V
$\Delta V_{GS(th)}$	$V_{GS(th)}$ Temperature Coefficient		---	2.6	---	mV/°C
$I_{DSS}$	Drain-Source Leakage Current	$V_{DS}=-24V, V_{GS}=0V, T_J=25^\circ C$	---	---	-1	uA
		$V_{DS}=-24V, V_{GS}=0V, T_J=55^\circ C$	---	---	-5	
$I_{GSS}$	Gate-Source Leakage Current	$V_{GS}=\pm 12V, V_{DS}=0V$	---	---	$\pm 100$	nA
$g_{fs}$	Forward Transconductance	$V_{DS}=-5V, I_D=-3A$	---	5.6	---	S
$Q_g$	Total Gate Charge (-4.5V)	$V_{DS}=-15V, V_{GS}=-4.5V, I_D=-3A$	---	11.9	---	nC
$Q_{gs}$	Gate-Source Charge		---	1.8	---	
$Q_{gd}$	Gate-Drain Charge		---	3	---	
$T_{d(on)}$	Turn-On Delay Time	$V_{DD}=-15V, V_{GS}=-4.5V, R_G=3.3\Omega, I_D=-3A$	---	6.6	---	ns
$T_r$	Rise Time		---	27.8	---	
$T_{d(off)}$	Turn-Off Delay Time		---	46.2	---	
$T_f$	Fall Time		---	20.6	---	
$C_{iss}$	Input Capacitance	$V_{DS}=-15V, V_{GS}=0V, f=1MHz$	---	920	---	pF
$C_{oss}$	Output Capacitance		---	73	---	
$C_{riss}$	Reverse Transfer Capacitance		---	71	---	

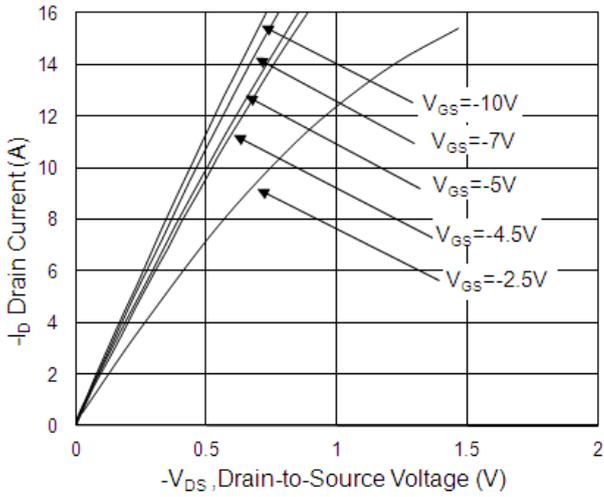
### Diode Characteristics

Symbol	Parameter	Conditions	Min	Typ	Max.	Uni
$I_S$	Continuous Source Current <sup>1,4</sup>	$V_G=V_D=0V$ , Force Current	---	---	-4.3	A
$V_{SD}$	Diode Forward Voltage <sup>2</sup>	$V_{GS}=0V, I_S=-1A, T_J=25^\circ C$	---	---	-1.2	V

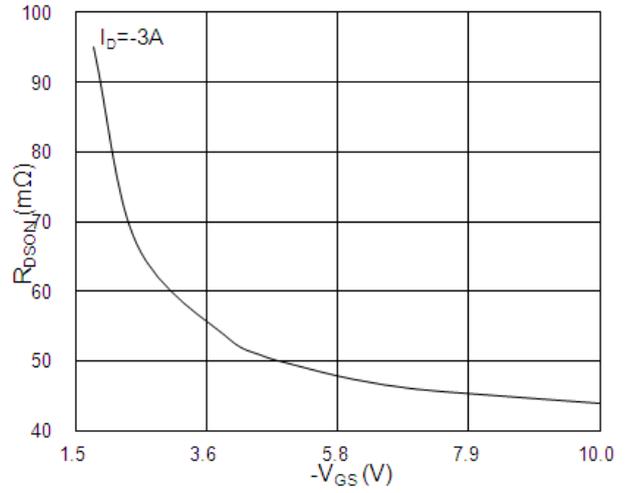
Note :

- 1.The data tested by surface mounted on a 1 inch<sup>2</sup> FR-4 board with 2OZ copper.
- 2.The data tested by pulsed , pulse width  $\leq 300\mu s$  , duty cycle  $\leq 2\%$
- 3.The power dissipation is limited by 150°C junction temperature
- 4.The data is theoretically the same as  $I_D$  and  $I_{DM}$  , in real applications , should be limited by total power dissipation.

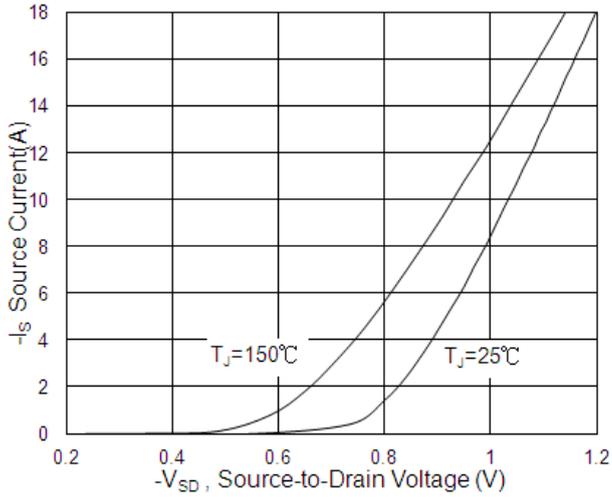
**Typical Characteristics**



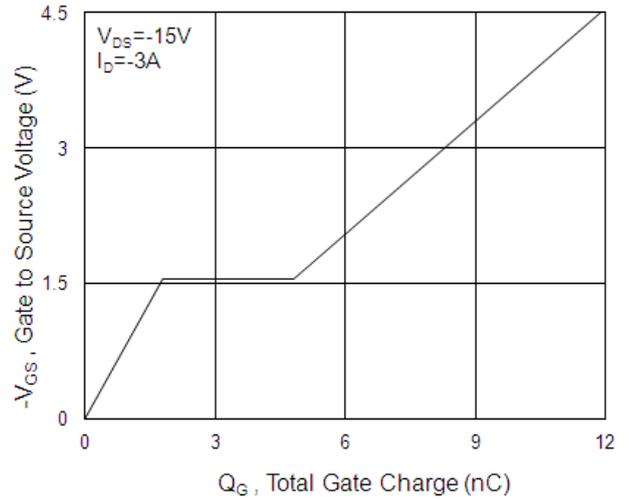
**Fig.1 Typical Output Characteristics**



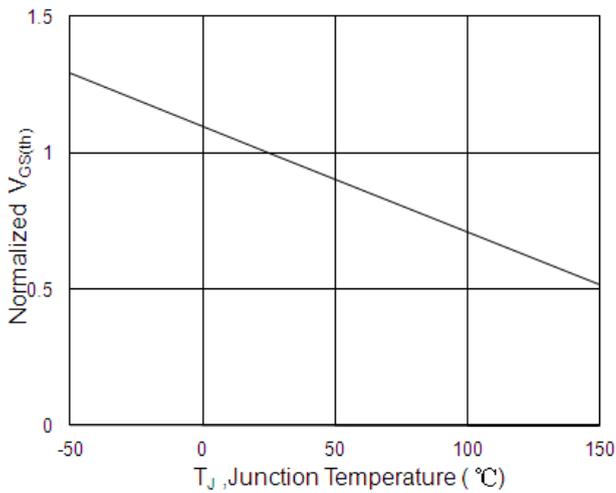
**Fig.2 On-Resistance vs. G-S Voltage**



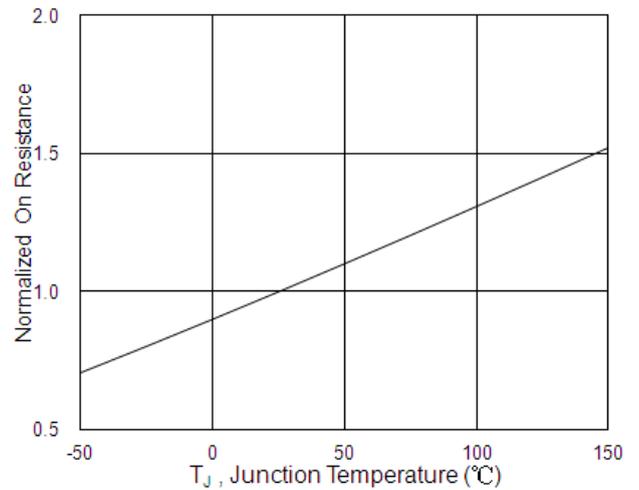
**Fig.3 Forward Characteristics Of Reverse**



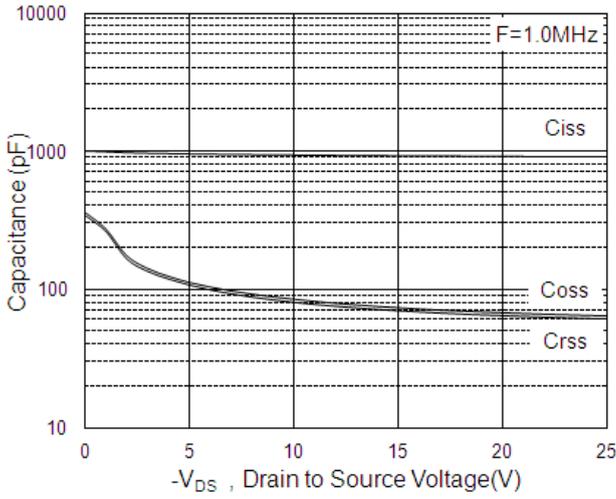
**Fig.4 Gate-Charge Characteristics**



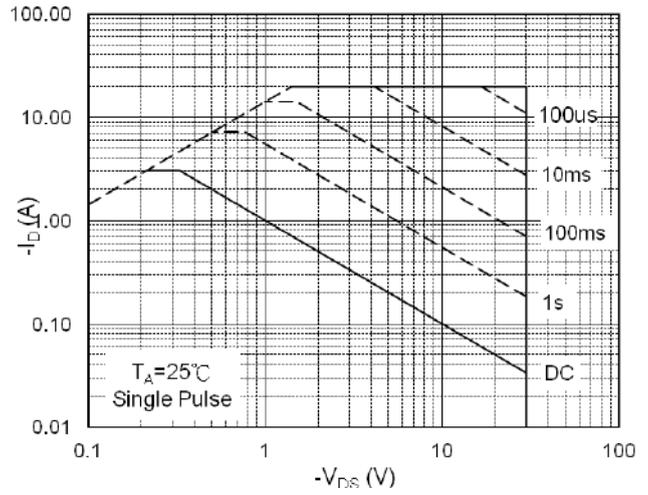
**Fig.5 Normalized  $V_{GS(th)}$  vs.  $T_J$**



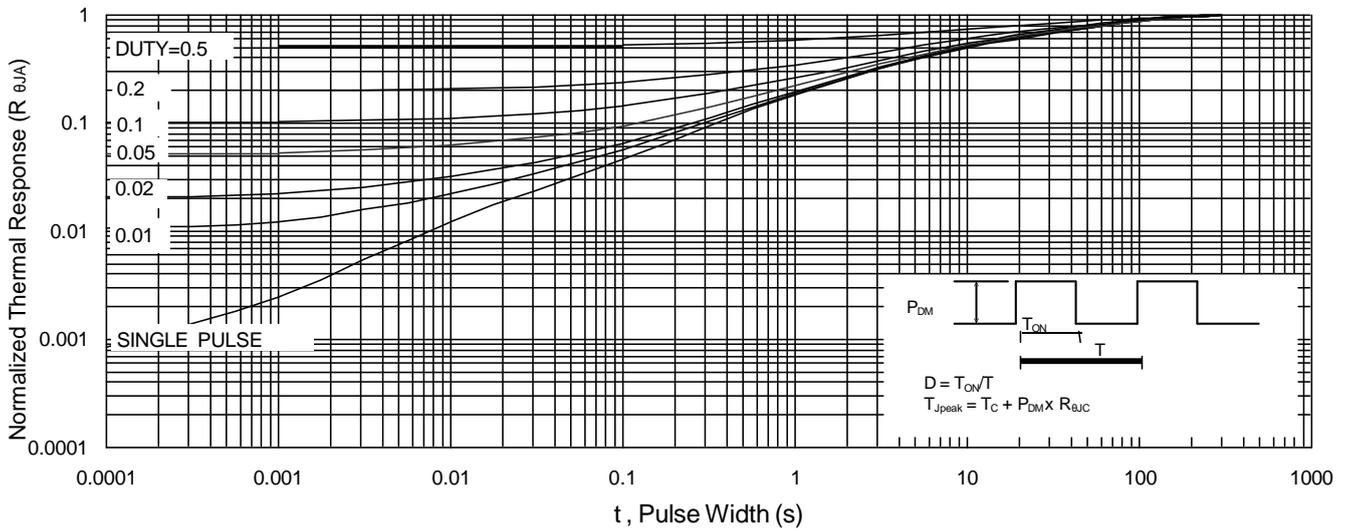
**Fig.6 Normalized  $R_{DS(on)}$  vs.  $T_J$**



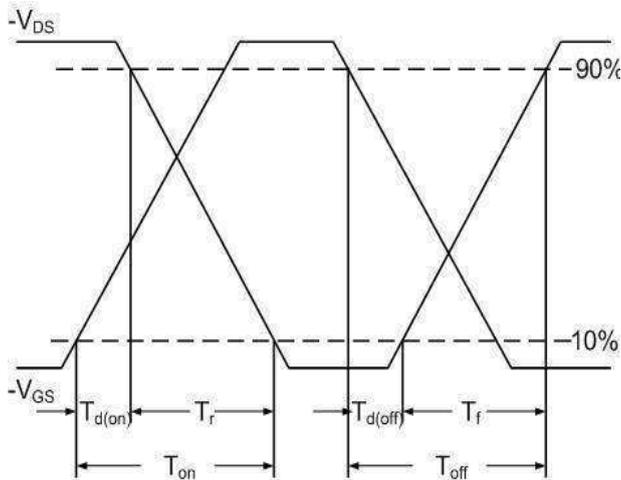
**Fig.7 Capacitance**



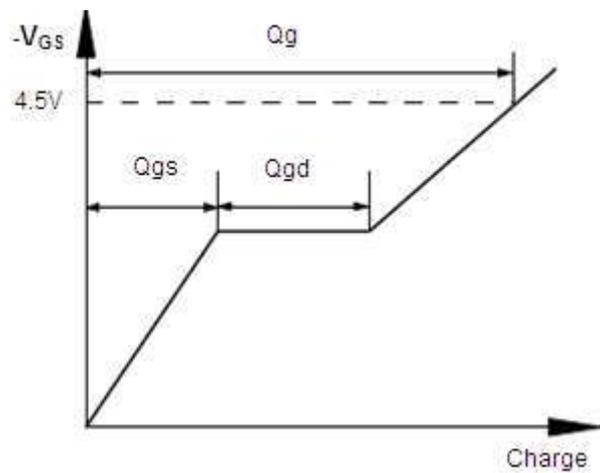
**Fig.8 Safe Operating Area**



**Fig.9 Normalized Maximum Transient Thermal Impedance**

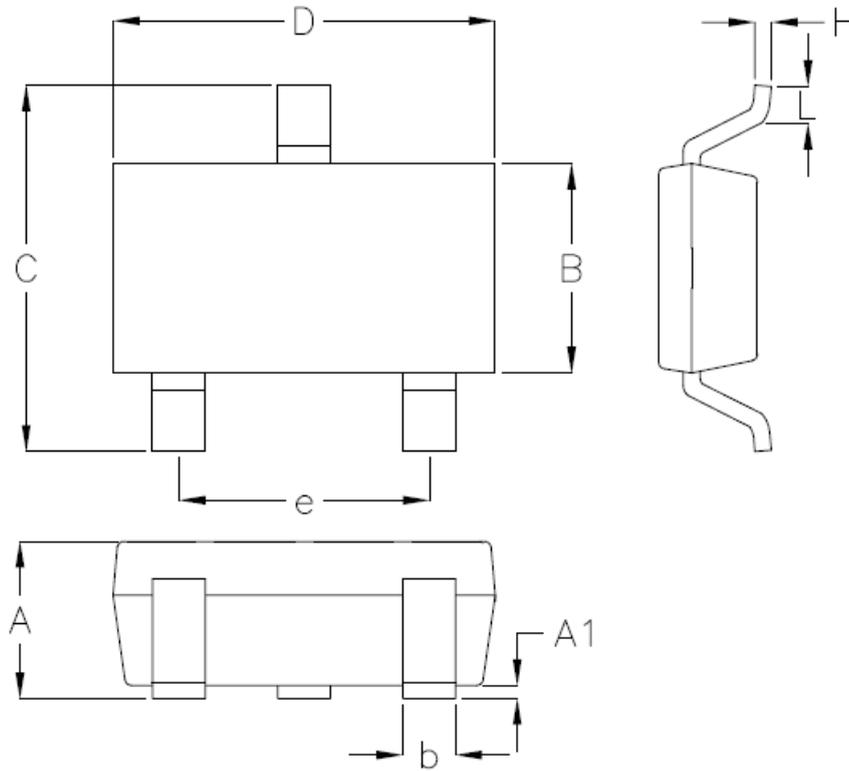


**Fig.10 Switching Time Waveform**



**Fig.11 Gate Charge Waveform**

## SOT-23S Package Outline



SYMBOLS	MILLIMETERS		INCHES	
	MIN	MAX	MIN	MAX
A	0.890	1.295	0.035	0.051
A1	0.000	0.152	0.000	0.006
B	1.200	1.400	0.047	0.055
b	0.300	0.508	0.012	0.020
C	2.100	2.640	0.083	0.104
D	2.692	3.099	0.106	0.122
e	1.793	2.007	0.070	0.079
H	0.080	0.254	0.003	0.010
L	0.300	0.610	0.012	0.024